



Narodowe Centrum
Badań i Rozwoju



Politechnika
Wroclawska

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LOW TEMPERATURE COFIRED CERAMICS:
TECHNOLOGY AND APPLICATIONS

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Prezentacja promująca Projekt
Modularne Detektory GEM (MGEM)
Nr POIR.04.01.02-00-0080/17

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LOW TEMPERATURE COFIRED CERAMICS: TECHNOLOGY AND APPLICATIONS

WITOLD NAWROT
KAROL MALECHA

THICK FILM MICROSYSTEM LABORATORY



HR EXCELLENCE IN RESEARCH



Wrocław University
of Science and Technology

BENEFITS OF CERAMIC MATERIALS

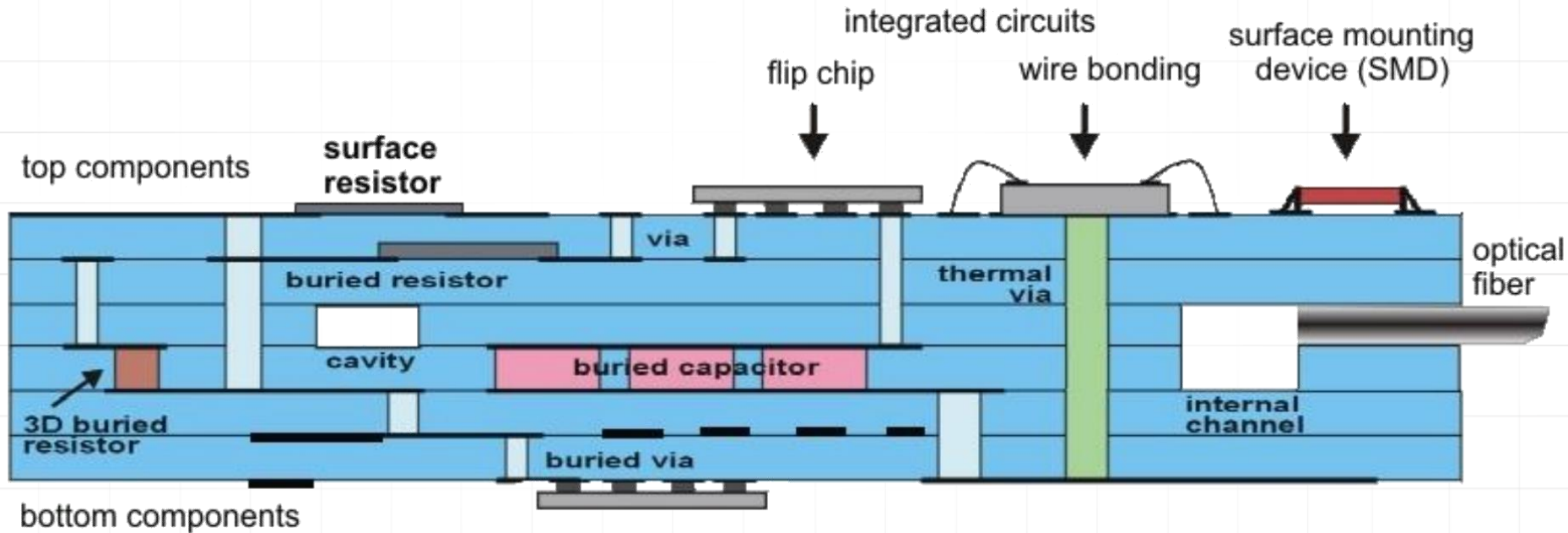
- High temperature stability
- High chemical resistance
- High insulation resistance and breakdown voltage
- Very hard
- Hermetic sealing capability
- Fine structuration
- Dense, multilayer interconnection capability
- Low dielectric losses
- Low thermal expansion

BENEFITS OF CERAMIC MATERIALS

	FR4	LTCC	Al ₂ O ₃
Relative permittivity (1 MHz)	4.8	7.8	9.5
Loss tangent	2.2	0.0140	0.0001
Thermal expansion [ppm/K]	13 - 18	5.8	7.3
Thermal conductivity [W/(m·K)]	0,4	3	10 - 35

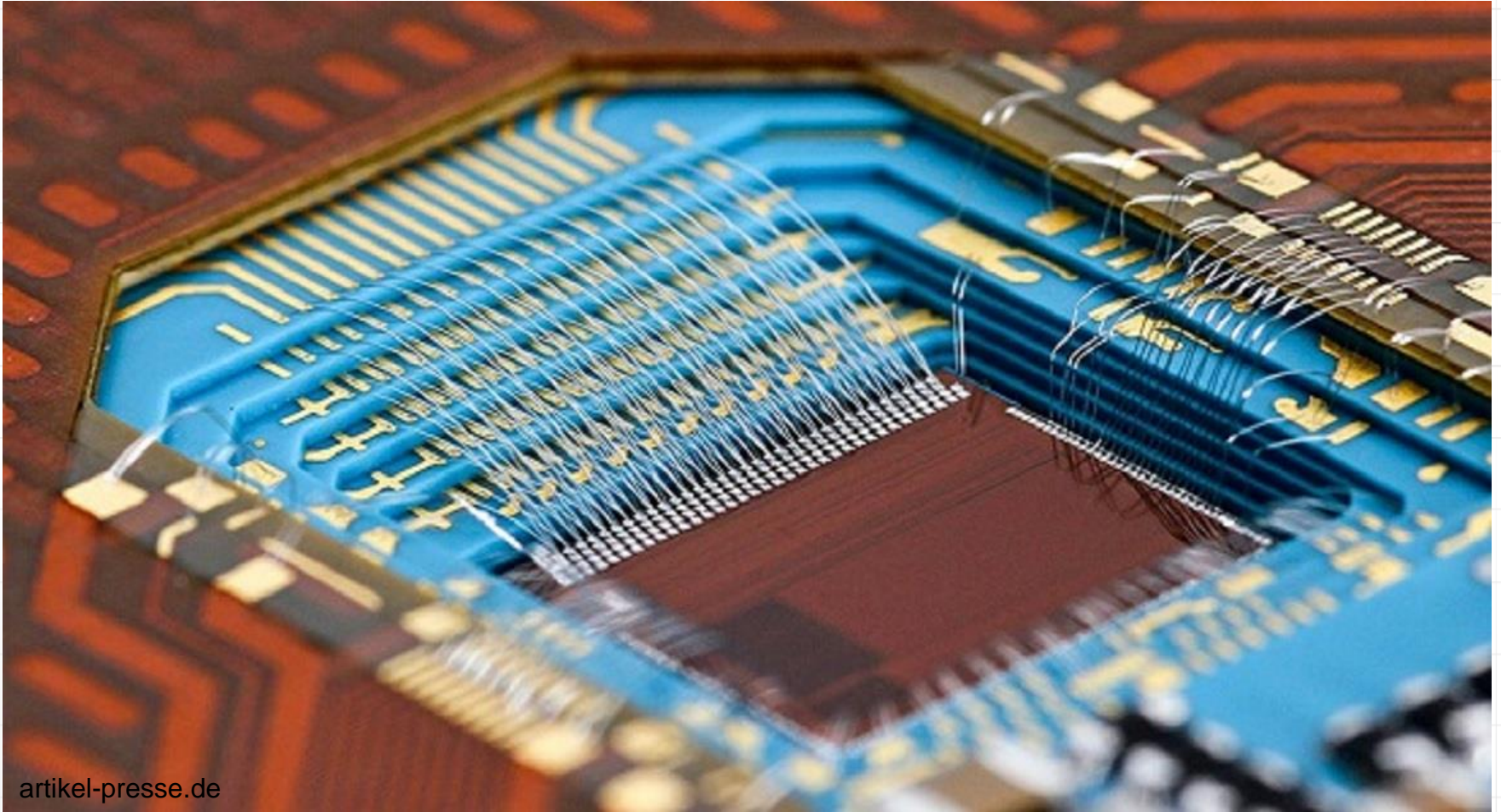
L. Golonka, K. Malecha, "Ceramic microsystems," Wrocław 2011;

LTCC CROSS SECTION



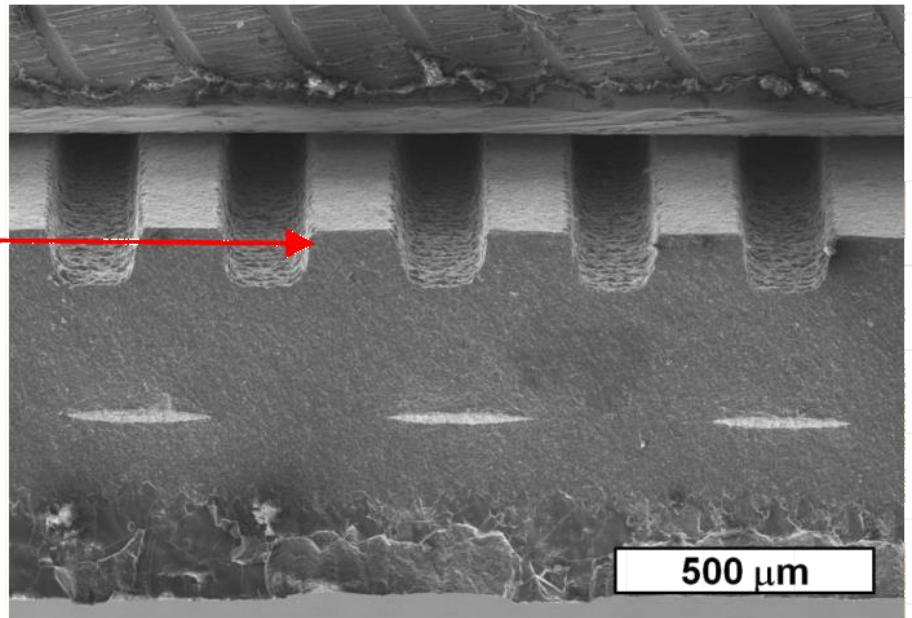
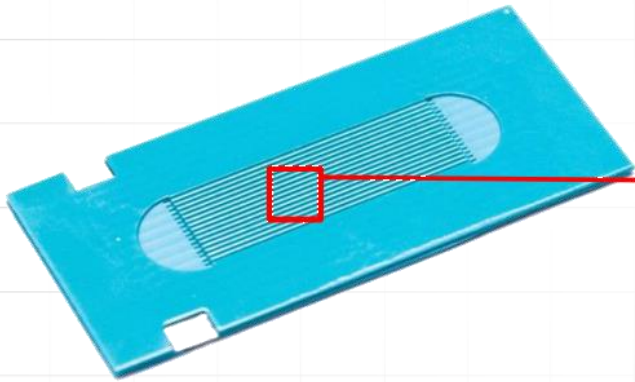
L. Golonka, K. Malecha, "Ceramic microsystems," Wrocław 2011;

DENSE MULTILAYER INTERCONNECTIONS



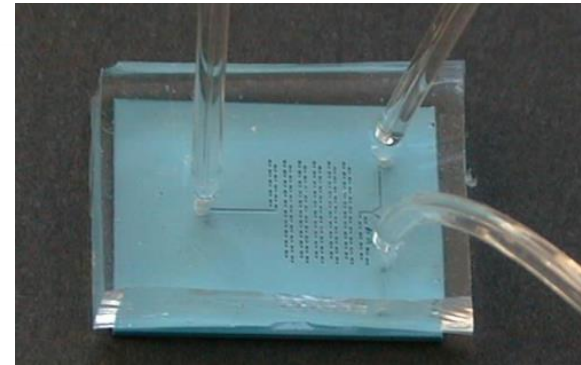
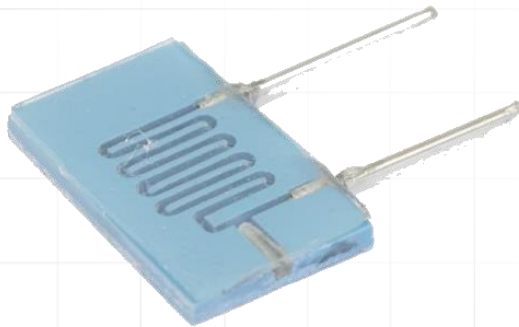
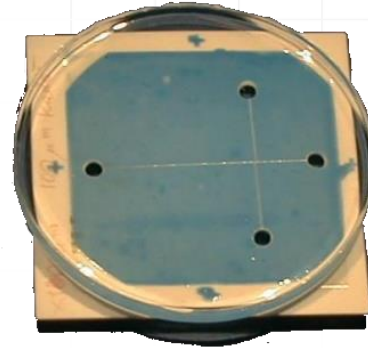
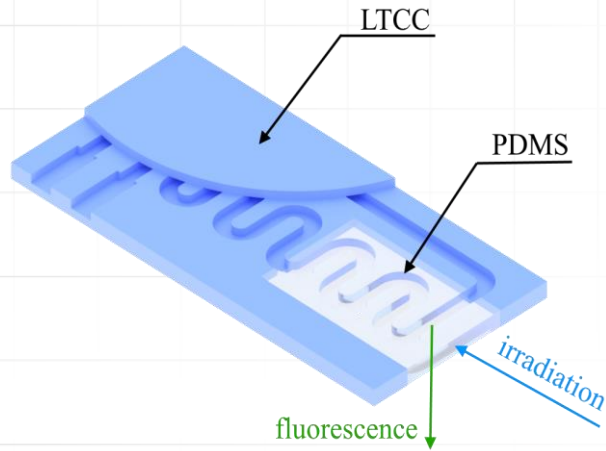
artikel-presse.de

FINE STRUCTURATION



K. Malecha, E. Remiszewska, D. G. Pijanowska "Surface modification of low and high temperature co-fired ceramics for enzymatic microreactor fabrication," Sensors and Actuators B: Chemical 190 pp. 873-880 (2014)

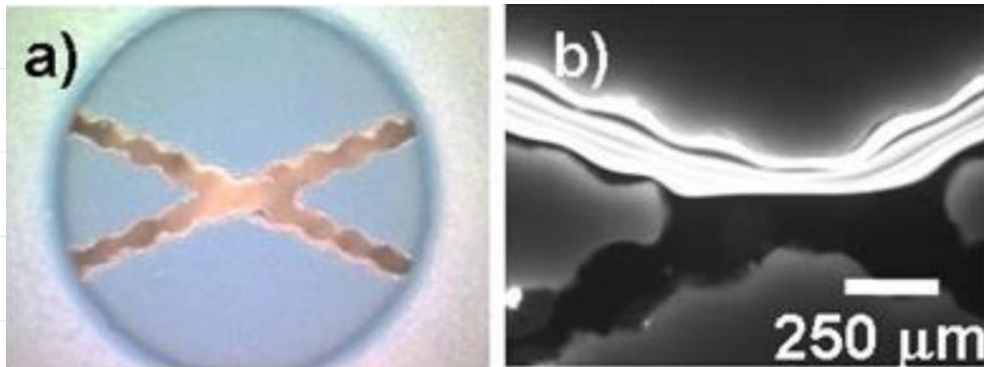
BONDING WITH PDMS



L. Golonka, K. Malecha, "Ceramic microsystems," Wroclaw 2011;

W. Nawrot, K. Malecha, "Preliminary studies for hybrid LTCC-PDMS fluorescence sensor," 42nd International Microelectronics and Packaging IMAPS Poland 2018 Conference

BONDING WITH GLASS

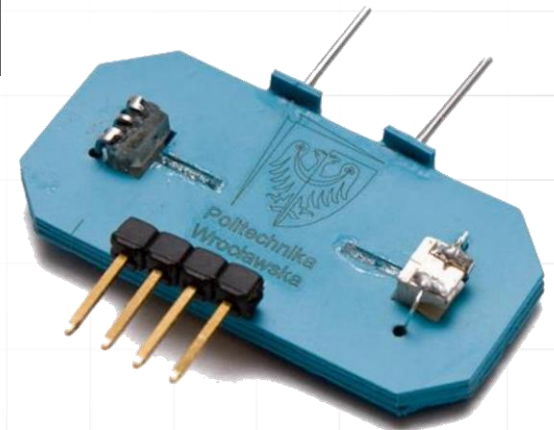
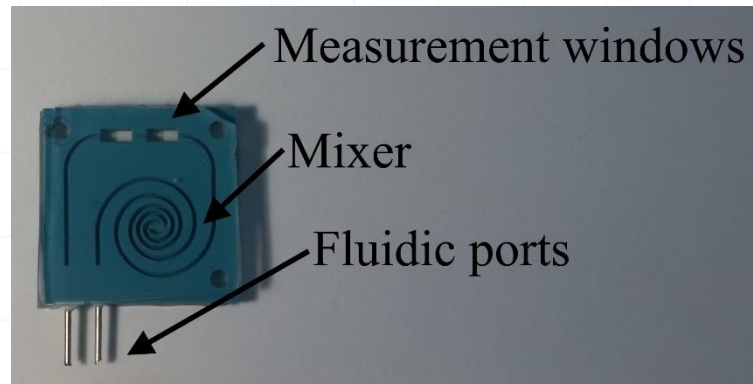


L. Golonka, K. Malecha, "Ceramic microsystems," Wroclaw 2011;

P. Bemnowicz, L. J. Golonka, "Integration of transparent glass window with LTCC technology for μTAS application,"

Jour. of the Eur. Cer. Soc., 30 (2010) 743-749.

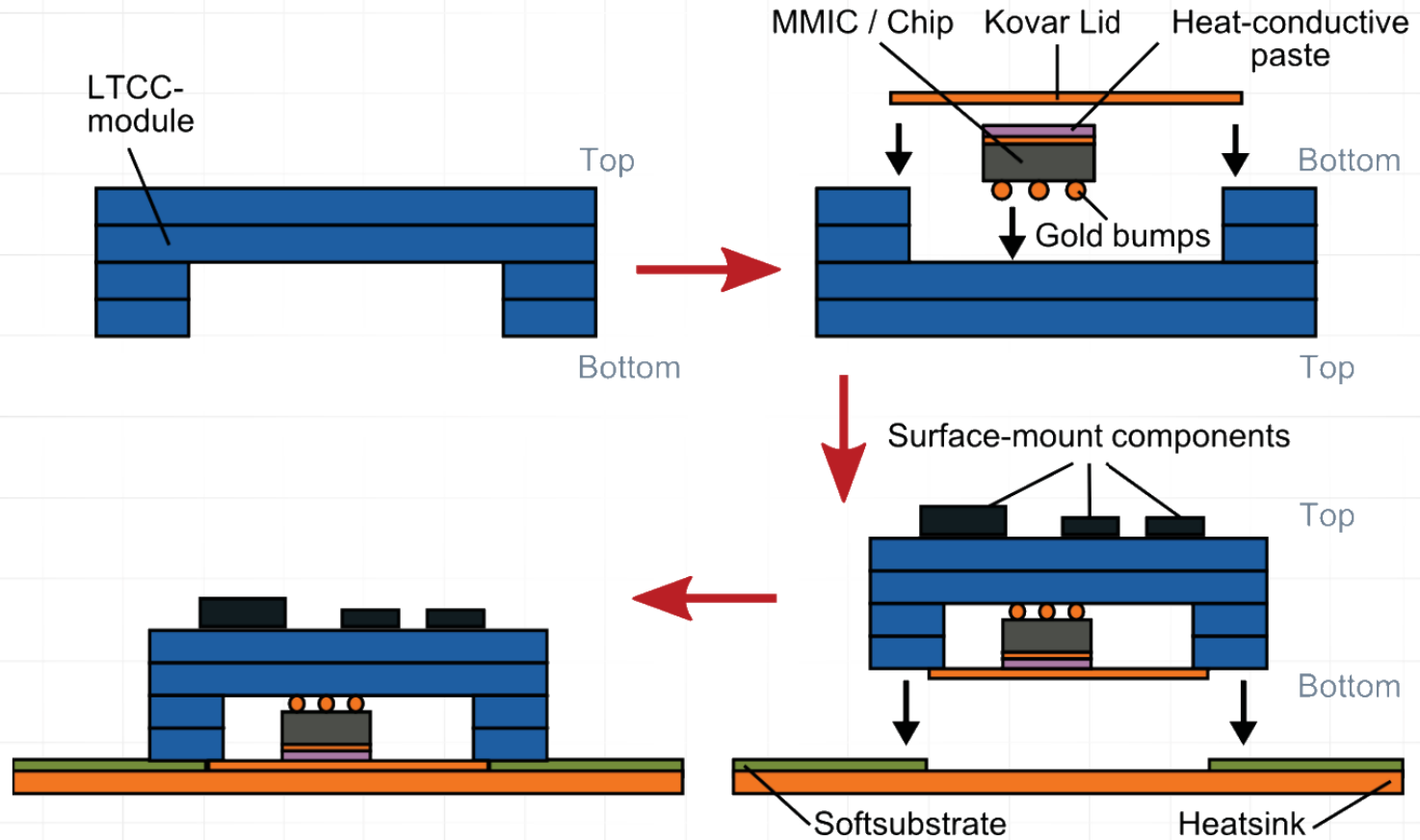
OPTICAL SENSORS



K. Malecha, M. Czok, A. Hetnar, A. Pawlik, H. Sztajer, L. J. Golonka "Micro Ceramic Cell Analyzer (MCCA) – Preliminary results, " Microelectronics Reliability 51 (7) pp. 1250-1252

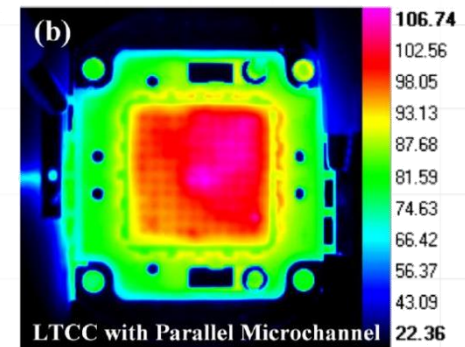
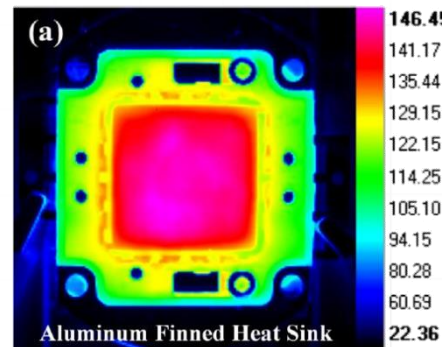
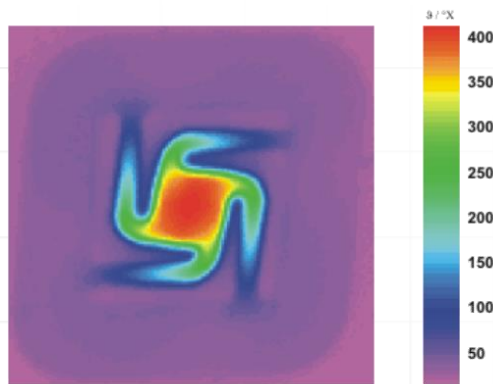
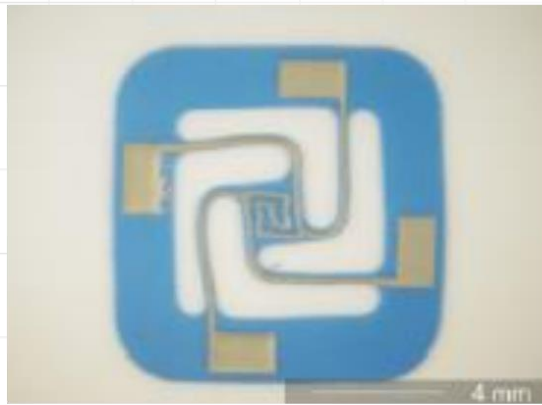
W. Nawrot, M. Fiedot-Toboła, K. Malecha "PDMS – LTCC Lab on Chip for photocatalytic effect analysis," 21st European Microelectronics and Packaging Conference (EMPC) & Exhibition, EMPC 2017

HERMETISATION



A. F. Jacob, "Packaging Approaches for Broadband Communication Systems," 11th European Microwave Integrated Circuits Conference 2016

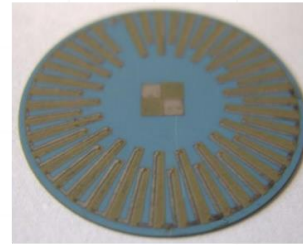
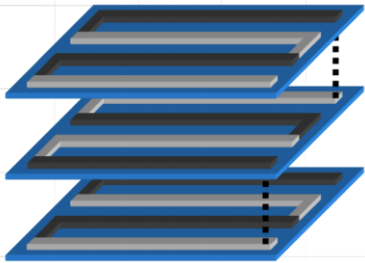
HEATING AND COOLING



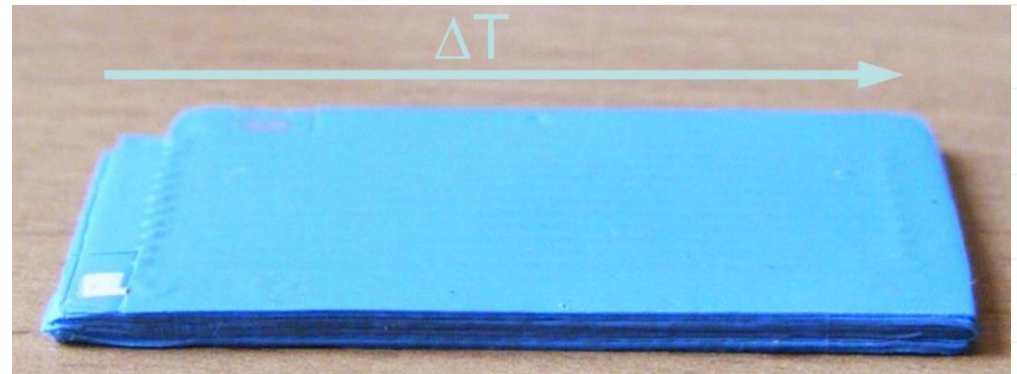
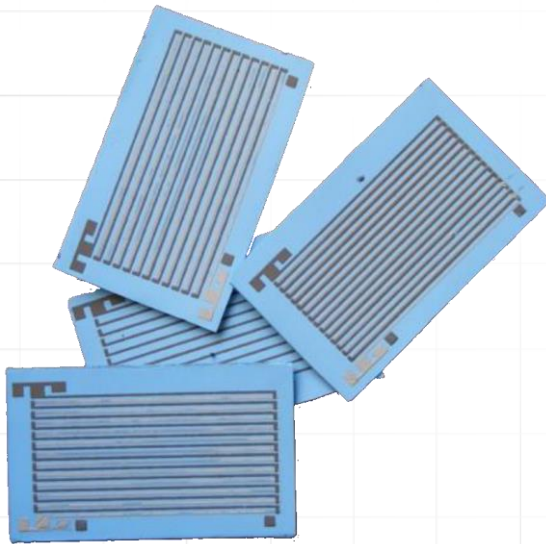
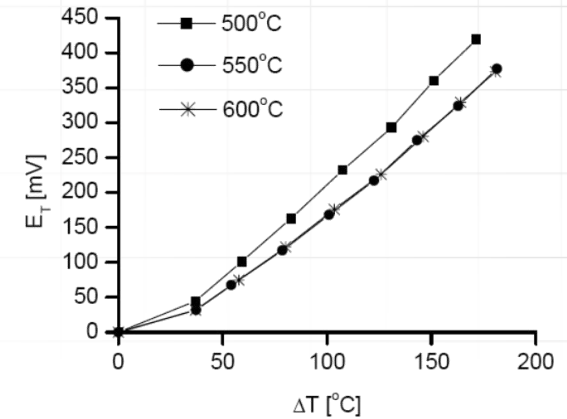
L.-Y. Zhang et al. / *International Journal of Heat and Mass Transfer* 84 (2015) 339–345

J. Kita, F. Rettig, R. Moos, K-H. Dr"ue, and H. Thust, "Hot-plate gas sensors – are ceramics better?," *Proc. 2005 IMAPS/AcerS 1st Int. Conf. and Exhib. on Ceramic Interconnect and Cer. Microsystem Technologies (CICMT), Baltimore (USA), 343–348 (2005).*

THERMOCOUPLES AND THERMOPILES

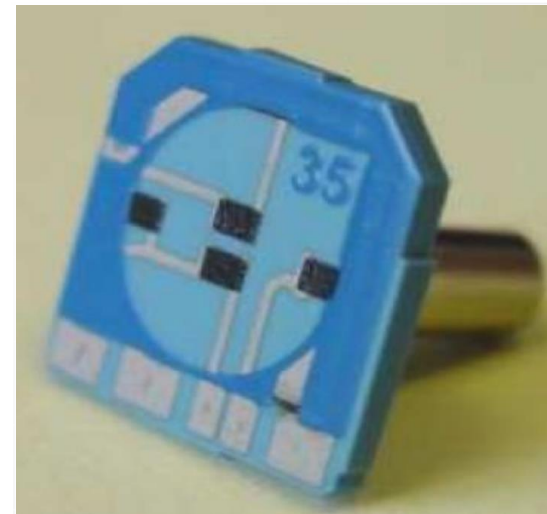
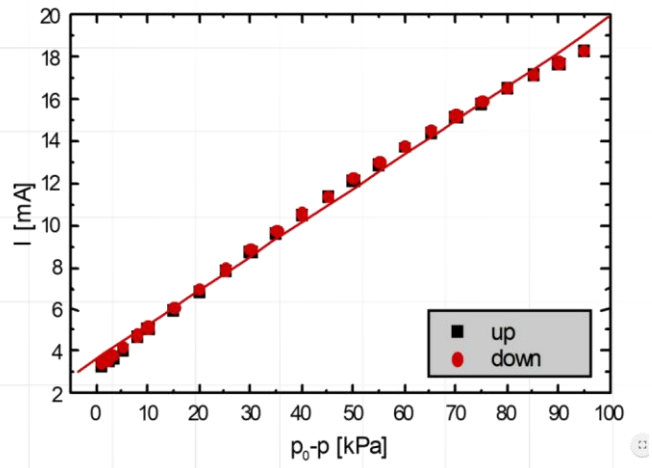
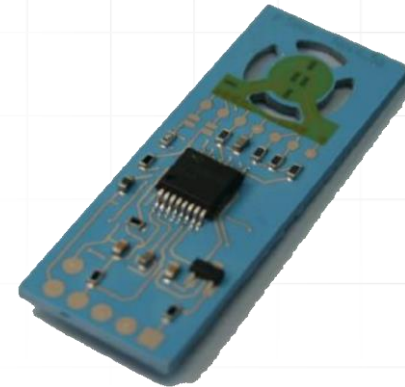
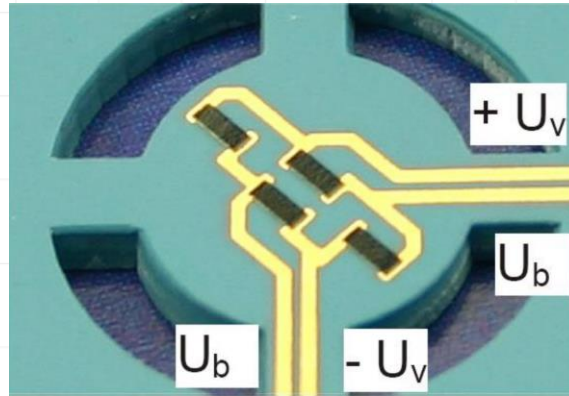


PdAg/TSG thermocouple

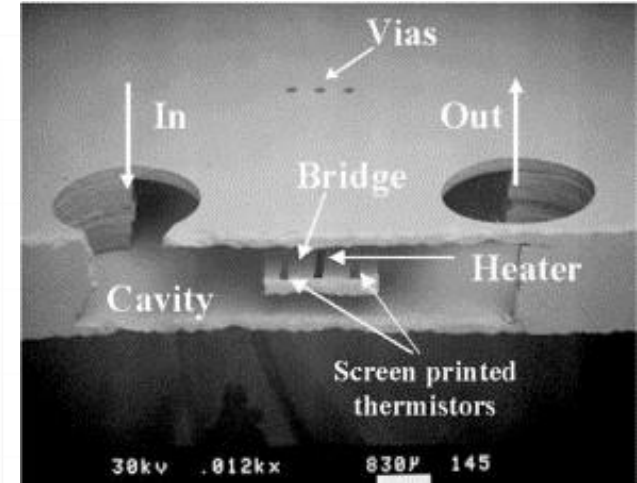
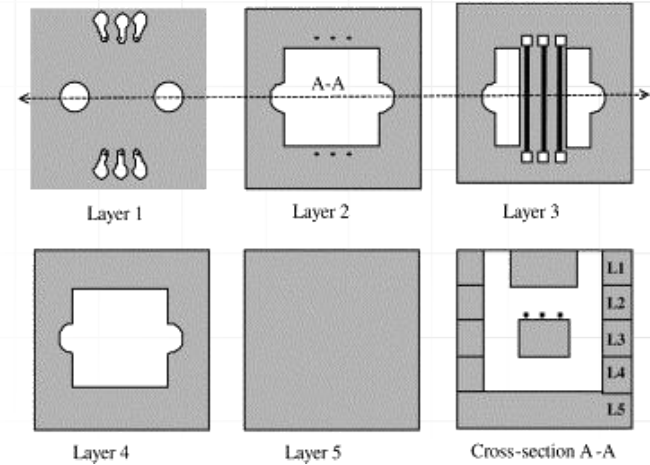
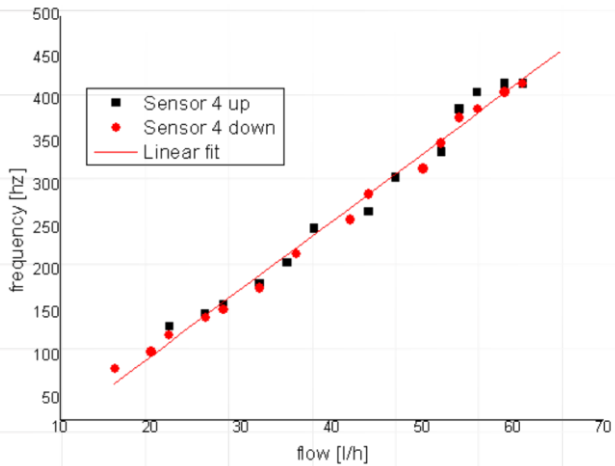
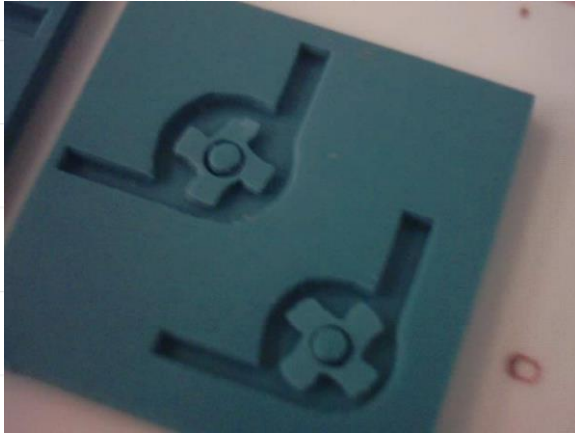


P. Markowski, A. Dziejczak "Planar and three-dimensional thick-film thermoelectric microgenerators," *Microelectronics Reliability* 48, (6)

PRESSURE SENSORS

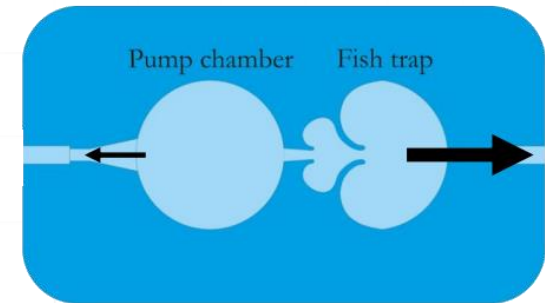
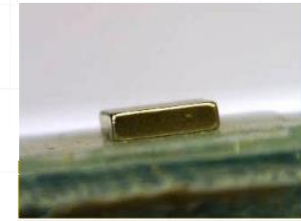
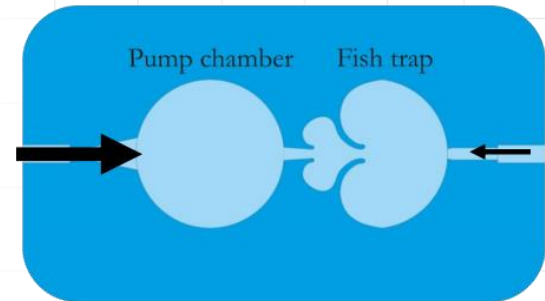
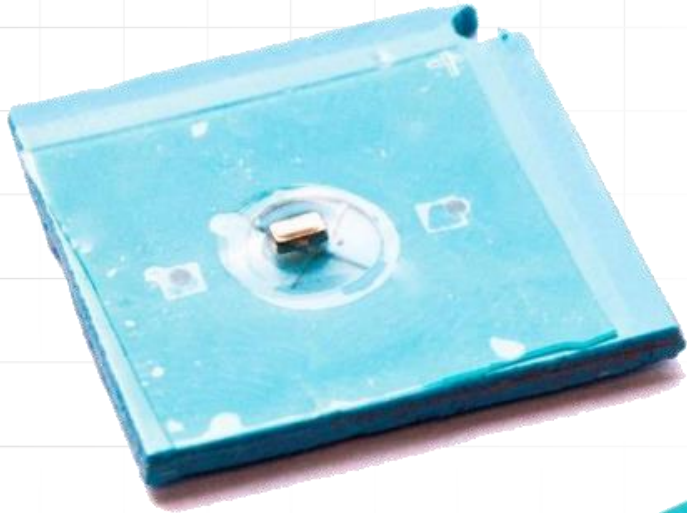


FLOW METRES



M.R. Gongora-Rubio, P. Espinoza-Vallejos, L. Sola-Laguna, J.J. Santiago-Aviles, "Overview of low temperature co-fired ceramics tape technology for meso-system technology (MsST)," *Sensors and Actuators A* 89 (2001) 222±241

ACTUATORS

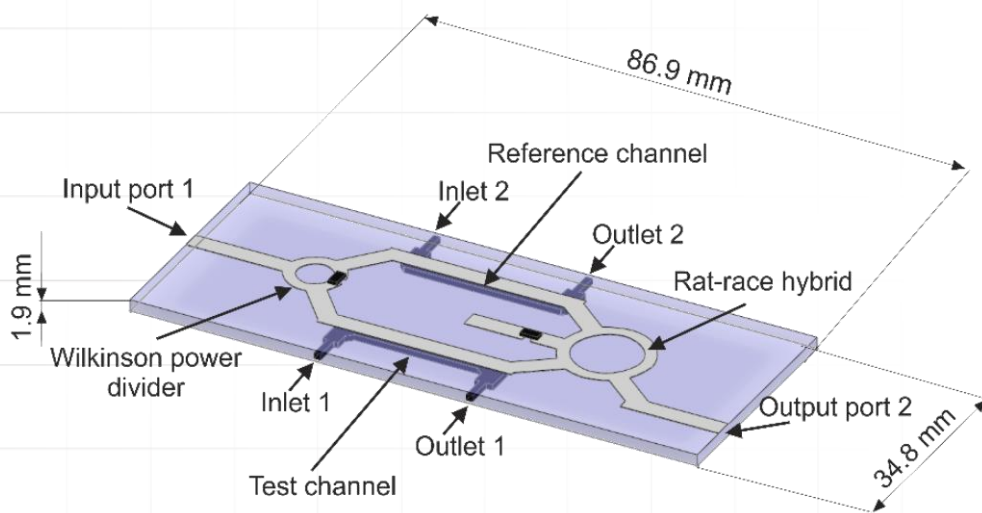


M. Czok, K. Malecha, L. Golonka "Electromagnetic valve made in low-temperature co-fired ceramics," *International Journal of Applied Ceramic Technology*. 2014, vol. 11, nr 3, s. 468-474.

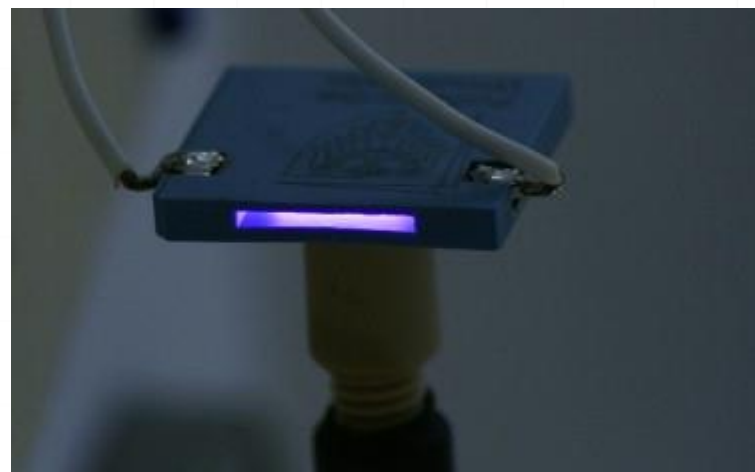
M. Czok, K. Malecha, L. Golonka "Electromagnetic pump made in a hybrid polymer-ceramic technology - preliminary results," *Journal of Chemistry and Chemical Engineering*. 2014, vol. 8, nr 10, s. 985-989.

MICROREACTORS

MICROWAVE MICROFLUIDICS



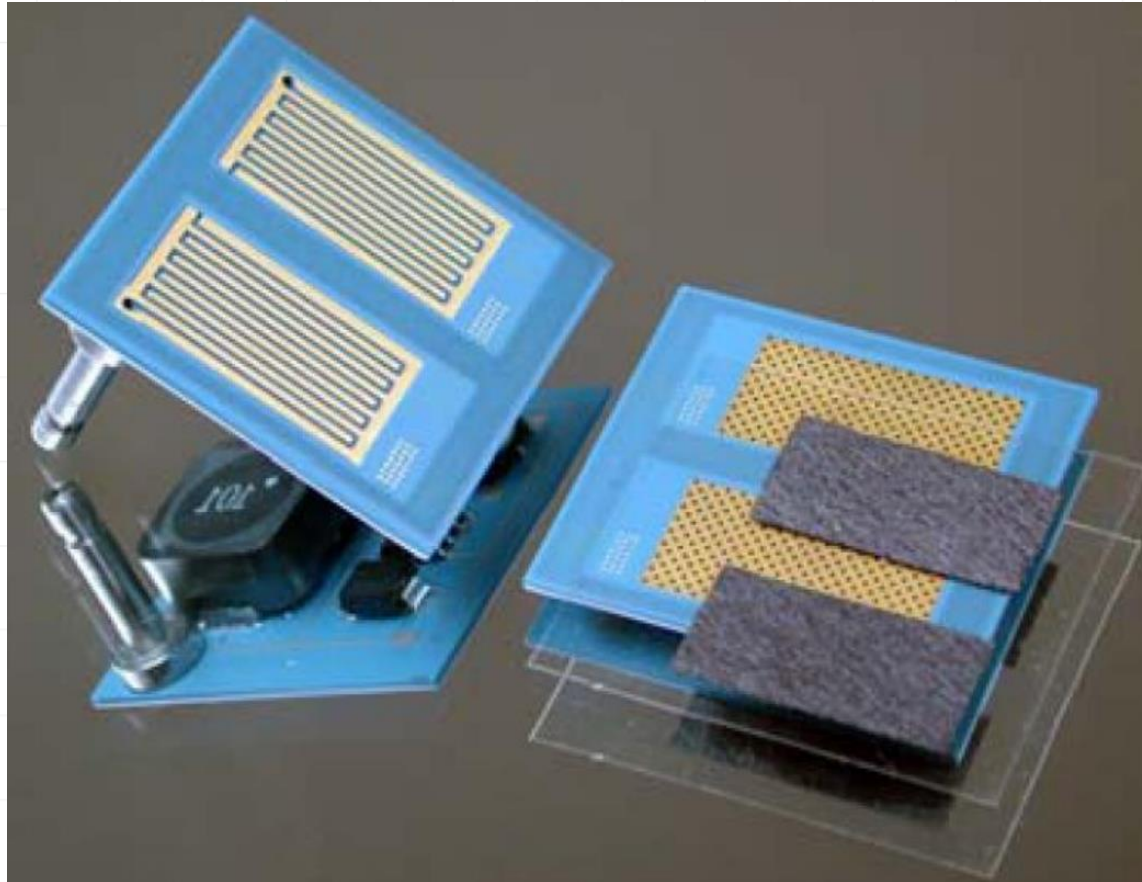
PLASMA MICROREACTORS



K. Malecha, L. Jasińska, A. Grytsko, K. Drzozga, P. Słobodzian, J. Cabaj "Monolithic Microwave-Microfluidic Sensors Made with Low Temperature Co-Fired Ceramic (LTCC) Technology", Sensors 19 (3) (2019)

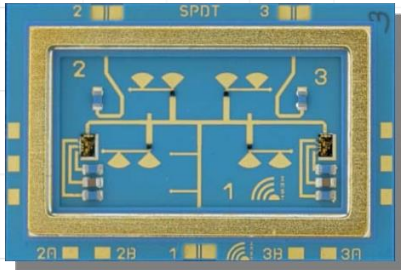
J. Macioszczyk, K. Malecha, H. Roguszczyk, S. Patela, L.J. Golonka "Low Temperature Co-fired Ceramics Plasma Generator for Atmospheric Pressure Gas Spectroscopy", Sensors and Actuators A: Physical 223, pp. 174-179 (2015)

FUEL CELLS

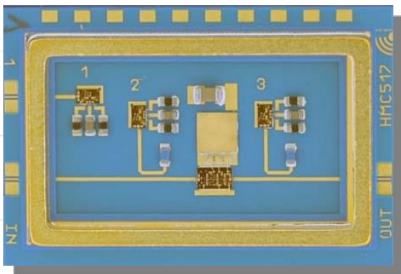


A. Michaelis "Application of ceramic technology for cost effective manufacturing of small fuel cell systems," International Conference and Exhibition on Ceramic Interconnect and Ceramic Microsystems Technologies (CICMT) 2007, Denver

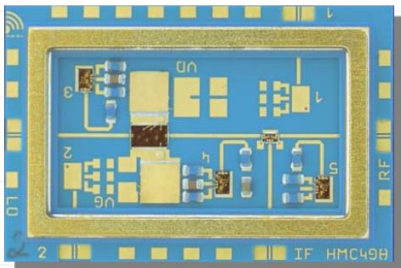
SPACE LTCC



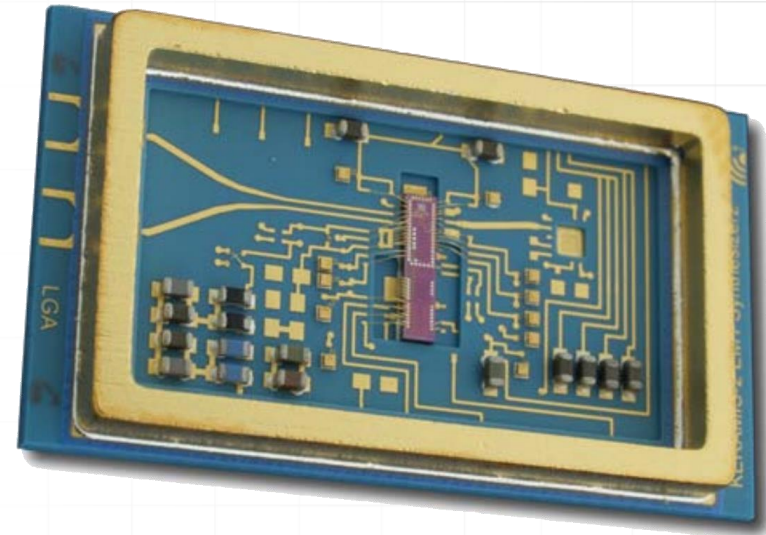
SPDT PIN Diodes Switch
with 2 Power Detectors



Low Noise Amplifier
with 3 Power Detectors



Medium Power Amplifier
Mixer and 3 Power Detectors

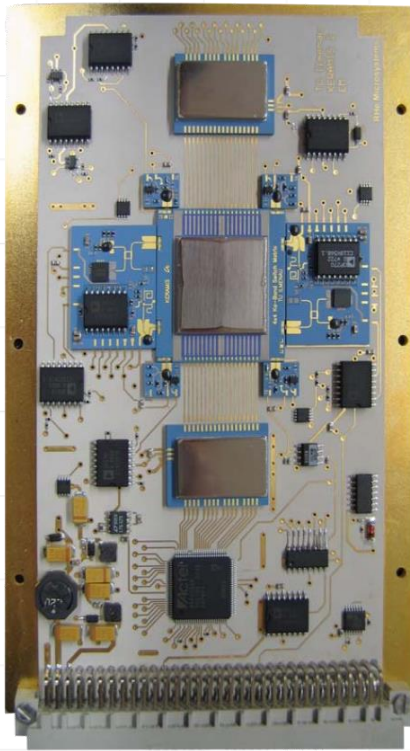


Synthesizer

I. Wolff, R. Kulke, T. Klein, "LTCC: A Space Qualified Integration and Packing Technology for Millimeter-Wave Systems," IEEE International Microwave Symposium 2012, Montreal, Canada

SPACE LTCC

I



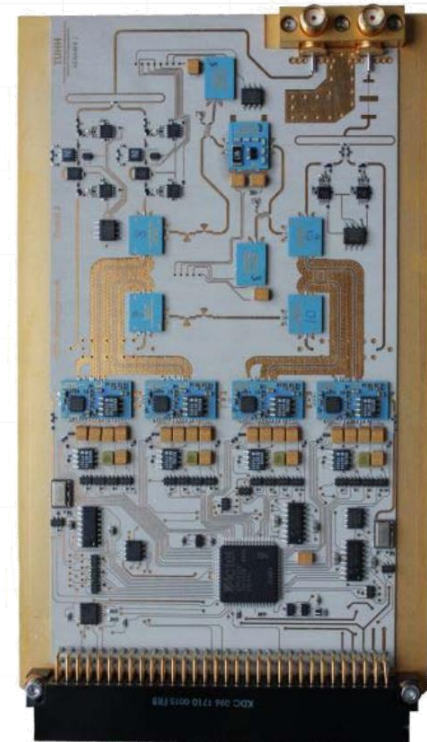
4x4 Switch matrix
TU-Ilmenau

II



Synthesizer
IMST

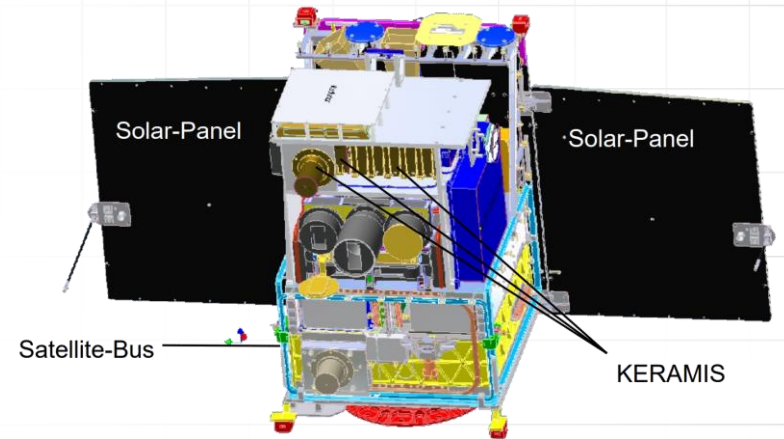
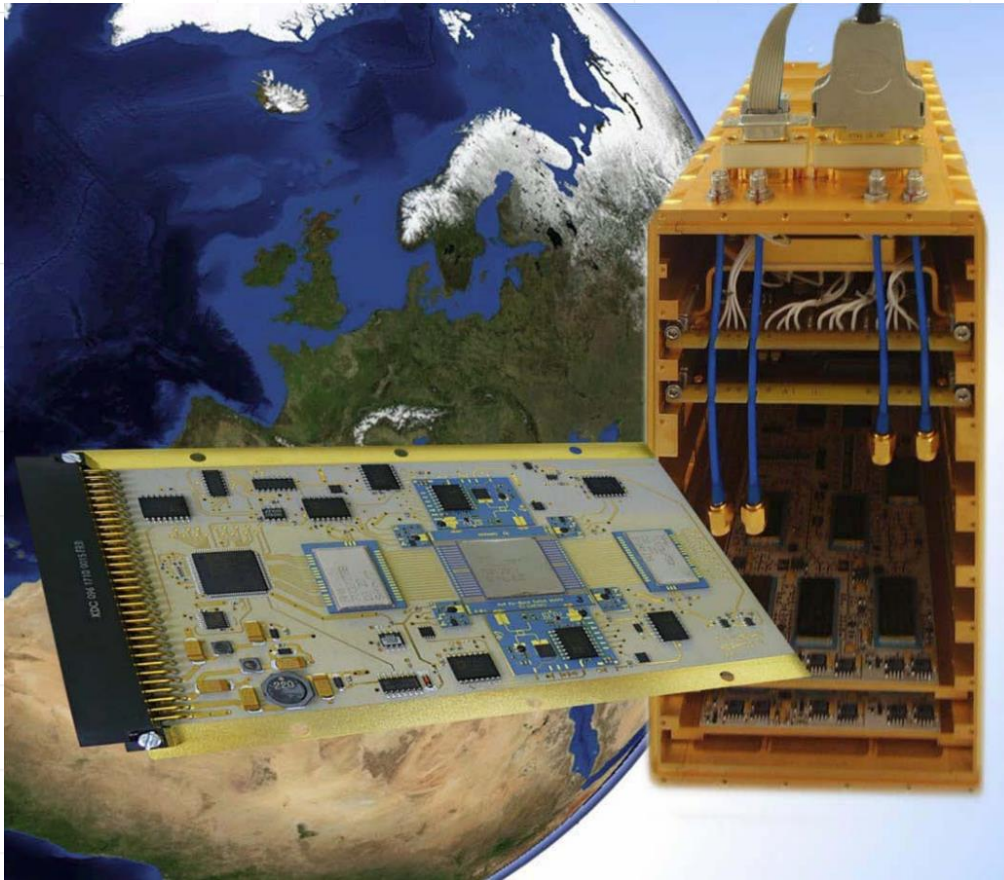
III



Transceiver
TU-Hamburg-Harburg

I. Wolff, R. Kulke, T. Klein, "LTCC: A Space Qualified Integration and Packing Technology for Millimeter-Wave Systems," IEEE International Microwave Symposium 2012, Montreal, Canada

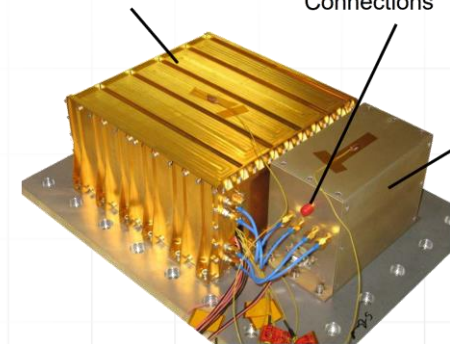
SPACE LTCC



KERAMIS-Box
with 3 Experiments

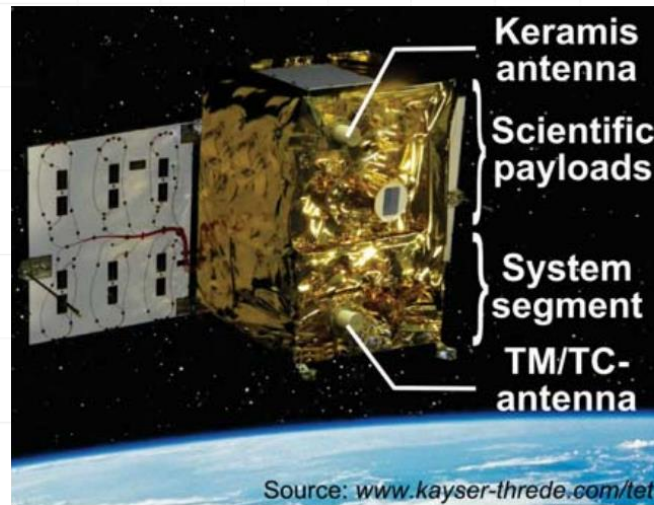
SMA and D-SUB
Connections

S-Band Transponder



I. Wolff, R. Kulke, T. Klein, "LTCC: A Space Qualified Integration and Packing Technology for Millimeter-Wave Systems," IEEE International Microwave Symposium 2012, Montreal, Canada

SPACE LTCC



Source: www.federal-space.ru

SUMMARY

- LTCC provides superior performance to PCB laminates
- Multilayer compact devices with fine interconnections can be developed using this technology
- Fine spatial structuration is possible, which enables development of microfluidic devices
- Wide range of sensors and actuators can be integrated
- Complex systems can be developed using this technology



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for Research and Development

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TECHTRA
TECHNOLOGY TRANSFER AGENCY



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